



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

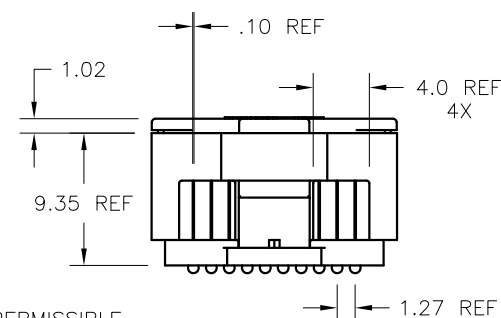
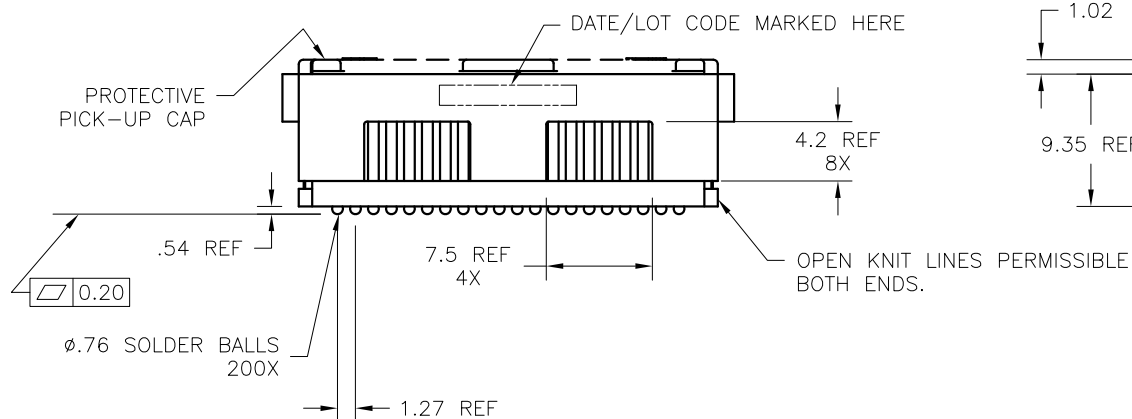
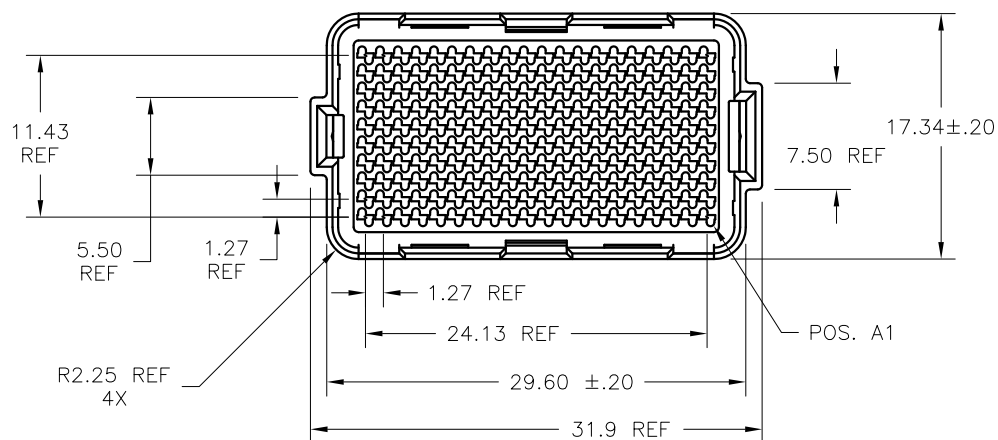
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



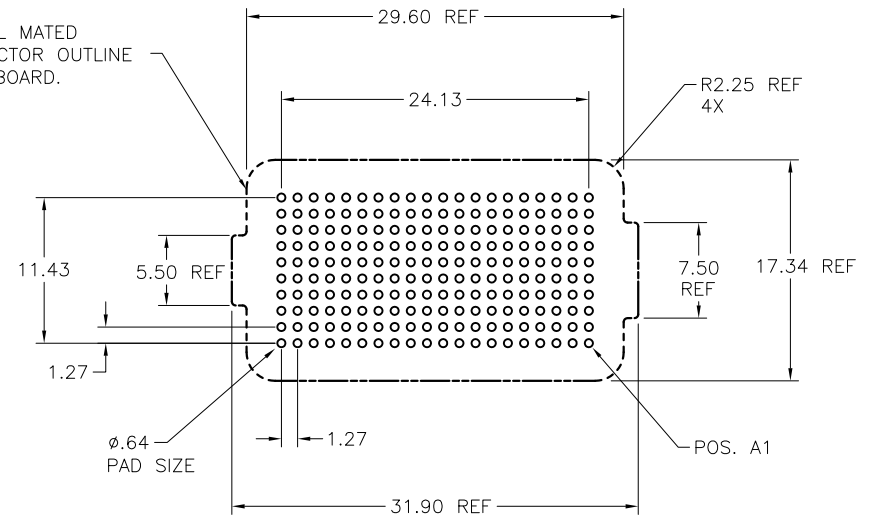
PRODUCT NUMBER
SEE TABLE— SHEET 2



mat'l. code SEE NOTE 1					surface ASME Y14.5 ☒		tolerance ASME Y14.5		projection 		product family MEG-Array				
lfr	ecn	no	dr	date	tolerances unless otherwise specified						title				
H	V11	-0029	HTB	2010-06-06	angles	length	X *3				6.0mm PLUG ASSEMBLY 10 X 20 = 200 POSITIONS				
J	V12	-0024	HTB	2012-04-03			XX *10								
K	V12	-0030	RE	2012-08-06	0° ±2°		XXX *050			scale	1:1				
L	V12	-0048	DCH	2012-11-20	dr	D. WAUGHEN		9999-09-08			dwg no				
—				—	engr	B. SPINK		9999-09-08			sheet 1 of 3				
F	V06	-0560	LP	2006-07-14	chr	B. SPINK		9999-09-08			84530				
G	V07	-0641	LP	2007-10-23	appd	B. SPINK		9999-09-08			type				
sheet index		revision		L	L	L									
				1	2	3									

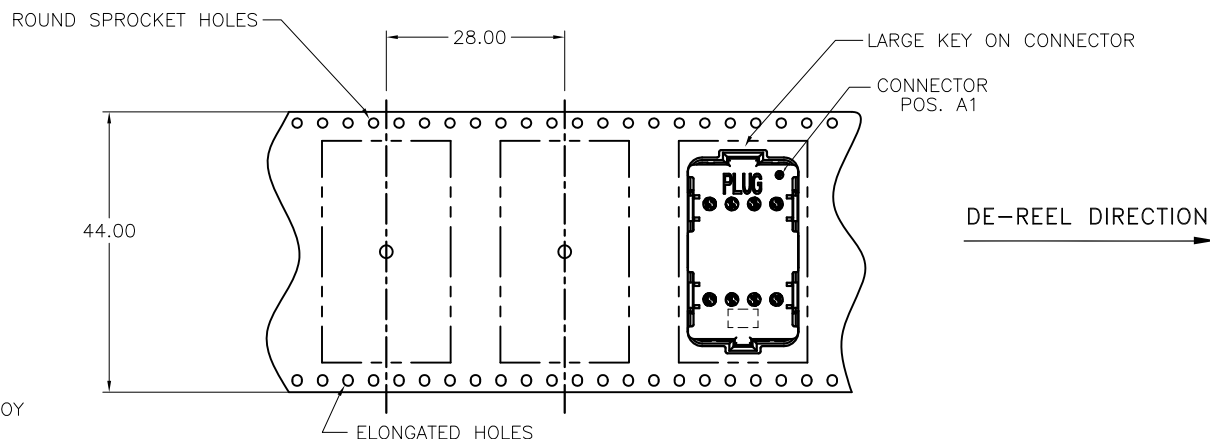
PRODUCT NO.	PICK-UP CAP (NATURAL OR BLACK COLOR)	CONTACT PLATING AND THICKNESS	SOLDER BALL	NOTES
84530-002	YES	15μ" (.38μm) Au	SnPb	
84530-002LF	YES	15μ" (.38μm) Au	LEAD FREE	6
84530-092	YES	15μ" (.38μm) GXT	SnPb	
84530-092LF	YES	15μ" (.38μm) GXT	LEAD FREE	6
84530-102	YES	30μ" (.76μm) Au	SnPb	
84530-102LF	YES	30μ" (.76μm) Au	LEAD FREE	6
84530-192	YES	30μ" (.76μm) GXT	SnPb	
84530-192LF	YES	30μ" (.76μm) GXT	LEAD FREE	6
84530-202	YES	50μ" (1.27μm) Au SPECIAL	SnPb	3 AND 4
84530-202LF	YES	50μ" (1.27μm) Au SPECIAL	LEAD FREE	3, 4 AND 6
84530-292	YES	50μ" (1.27μm) GXT SPECIAL	SnPb	3 AND 4
84530-292LF	YES	50μ" (1.27μm) GXT SPECIAL	LEAD FREE	3, 4 AND 6
84530-A02	YES	30μ" (.76μm)	SnPb	7
84530-A02LF	YES	30μ" (.76μm)	LEAD FREE	6 AND 7
84530-302	YES	15μ" (.38μm) Au SPECIAL	SnPb	7
84530-302LF	YES	15μ" (.38μm) Au SPECIAL	LEAD FREE	6 AND 7
84530-402	YES	30μ" (.76μm) Au SPECIAL	SnPb	7
84530-402LF	YES	30μ" (.76μm) Au SPECIAL	LEAD FREE	6 AND 7
84530-502	YES	Au SPECIAL	SnPb	3, 4 AND 7
84530-502LF	YES	Au SPECIAL	LEAD FREE	3, 4, 6 AND 7

STENCIL MATED
CONNECTOR OUTLINE
ONTO BOARD.



BOARD PATTERN

mat'l. code	surface	tolerance	projection	product family
SEE NOTE 1	ASME Y14.5	ASME Y14.5		MEG-Array
ltr	ecr no	dr	date	title
L				6.0mm PLUG ASSEMBLY
				10 X 20 = 200 POSITIONS
				dwg no
				84530
				type
				CUSTOMER Drawing
sheet index	revision sheet			sheet 2 of 3 size
				A4

PRODUCT NUMBER
 SEE TABLE-SHEET 2


NOTES:

- ①. MATERIAL:
 HOUSING: LCP
 CONTACT: COPPER ALLOY
- PLATING:
 CONTACT: (SEE TABLE ON SHEET 2)
 SOLDER BALL: (SEE TABLE ON SHEET 2)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu
2. OVERALL BOARD-TO-BOARD STACK HEIGHTS
 AVAILABLE USING THIS CONNECTOR (84530):
- | MATED HEIGHT | WITH RECPT. P/N | -2XX PLATING |
|--------------|-----------------|--------------|
| 10mm | 84517 | SEE NOTE 2 |
| 12mm | 55724 | |
| 14mm | 84535 | SEE NOTE 3 |
- ③. PLATING FOR INDICATED -2XX SERIES PART NOS.
 MEET THE REQUIREMENTS OF GR-1217-CORE,
 CENTRAL OFFICE ENVIRONMENT, (25 YEAR LIFE EXPECTANCY).
- ④. PLATING FOR INDICATED -2XX SERIES PART NOS. IS
 Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET
 REQUIREMENTS OF TELCORDIA GR-1217-CORE:
 CENTRAL OFFICE ENVIRONMENT.
- ⑤. FOR PROPER APPLICATION FOLLOW FCI APPLICATION
 SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL
 NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS
 DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE
 PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH
 LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE
 FCI APPLICATION SPECIFICATION.

- ⑥. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
 OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004
 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT
 CODE NUMBER MARKED ON EACH PART BY HAVING AN "X"
 IN THE SEVENTH CHARACTER POSITION.
- ⑦. 84530-A02 AND -A02LF ARE CUSTOMER SPECIALS.

12. A  SYMBOL WILL BE NEXT TO ANY DIMENSION, NEW VIEW OR
 NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT
 DRAWING REVISION

mat'l. code SEE NOTE 1				surface ASME Y14.5	tolerance ASME Y14.5	projection 	product family MEG-Array	
ltr	ecr no	dr	date	tolerances unless otherwise specified		MM scale 1:1	title 6.0mm PLUG ASSEMBLY 10 X 20 = 200 POSITIONS	
L				angles	X ±3 XX ±10 XXX ±050		dwg no	
				0° ±2°			sheet 3 of 3	
				dr	D. WAUGHEN 1999-09-08		size A4	
				engr	B. SPINK 1999-09-08		84530	
				chr	B. SPINK 1999-09-08		type	
				appd	B. SPINK 1999-09-08		CUSTOMER Drawing	
sheet index	revision sheet							